Panasonic

ideas for life

FOR BOARD-TO-BOARD AND BOARD-TO-FPC CONNECTION

NARROW PITCH (0.4mm) CONNECTORS P4S SERIES









Socket

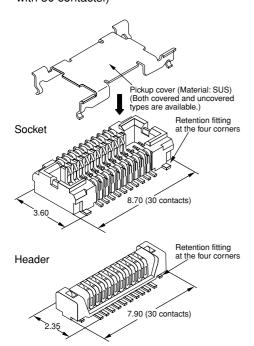
Header

FEATURES

1. Space saving

Compared to the currently sold P4 series with retention fitting, 38% space is saved in the socket and 34% space saved in the header.

This will contribute to weight and size savings in devices. (Comparison made with 30 contacts.)



2. Strong resistance to adverse environments! Utilizes

"TDUGH CONTRET" construction for high contact reliability.

1) Contacts are highly resistant to shock caused by dropping and employ our original bellows contact construction.

Contacts are formed by bending a thin metal sheet, which provides the contact parts with adequate spring characteristics ensuring greater resistance to prying forces and drop impacts.



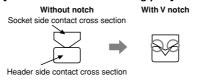
Note: If extra resistance to shock caused by dropping is required, we recommend using our previous P4 Series.

2) V notch construction used for excellent resistance against foreign matters.

• What is V notch construction?

By using the edge for the contacting part and increasing contact pressure per unit area, the effectiveness in removing flux and contaminants is increased compared to its predecessor. This is also effective in preventing the trapping of contaminants.

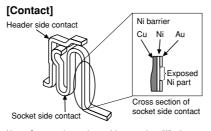
[Cross section of contacting part]



3) Use of Ni barrier construction is standard. Highly effective against solder creeping.

● What is Ni barrier construction?

By providing an exposed nickel part on the gold (Au) plated contact, solder creeping is prevented despite the ultra low profile.

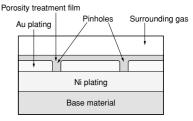


Note: Construction makes solder creeping difficult because header side is formed at the same time.

4) Porosity treatment applied for improved resistance against corrosion.

What is porosity treatment?

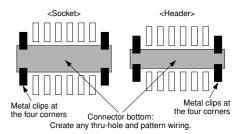
This treatment consists of coating the surface with a very thin film to seal pinholes in the gold plating. This porosity treatment technology ensures the same contact reliability for thin gold plating as that of thick gold plating.



- Improvement in insertion/removal durability
- Improvement in resistance to corrosion
- Improvement in contact reliability for digital signals

3. Greater flexibility in connector placement.

Pattern wiring to the connector bottom is possible because the undersurface of the connector is constructed with a molded covering.



Automatic mounting inspection is facilitated by the gull-wing terminal shape which makes mounting verification easy.

5. Compliance with RoHS' Directive Environmentally friendly, the connectors' comply with Europe's RoHS' Directive. Cadmium, lead, mercury, hexavalent, chromium, PBB and PBDE are not used.

11/2005

APPLICATIONS

Compact portable devices "Cellular phones, DVC, Digital cameras, etc"

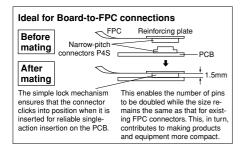


TABLE OF PRODUCT TYPES

P4S (0.4mm pitch): With retention fitting



☆: Available for sale

	Mated height		1.5mm	3.0mm			
Ī		10	☆				
		16	☆				
		20	☆				
		22	☆				
		24	☆				
		26	☆				
		28	☆				
		30	☆	☆			
	ıcts	32	☆				
	onte	34	☆				
	ρ	36	☆				
	o Ye	38	☆				
	ηpe	40	☆				
	Number of contacts	44	☆				
		50	☆				
		54	☆				
		56	☆				
		60	☆				
		70	☆				
		80	☆	☆			
		90	☆				
_		100	☆				
	Make. The skew dead town a series						

Note: The standard type comes without positioning bosses. Connectors with positioning boss are available for on-demand production.

ORDERING INFORMATION

AXT		
3: Narrow Pitch Connector P4S (0.4 mm pitch) Socket 4: Narrow Pitch Connector P4S (0.4 mm pitch) Header		
Number of contacts (2 digits)		
Mated height <socket> 1: For mated height 1.5 mm 2: For mated height 3.0 mm <header> 1: For mated height 1.5 mm 3: For mated height 3.0 mm</header></socket>		
Functions <socket> 5: With pickup cover, with positioning bosses 6: With pickup cover, without positioning bosses <header> 1: No pickup cover, with positioning bosses 2: No pickup cover, without positioning bosses</header></socket>	_	
Surface treatment (Contact portion / Terminal portion) <socket> 4: Ni plating on base, Au plating on surface (for Ni barrier product available)</socket>		

4: Ni plating on base, Au plating on surface

PRODUCT TYPES * TOUGH CONTRCT

		Part nu	mber	Packing		
Mated height	Number of contacts	Socket (Ni barrier product: Header Available)		Inner carton	Outer cartor	
	10	AXT310164	AXT410124			
	16	AXT316164	AXT416124			
	20	AXT320164	AXT420124			
	22	AXT322164	AXT422124			
	24	AXT324164	AXT424124			
	26	AXT326164	AXT426124		6,000 pieces	
	28	AXT328164	AXT428124			
	30	AXT330164	AXT430124			
	32	AXT332164	AXT432124			
	34	AXT334164	AXT434124			
1.5mm	36	AXT336164	AXT436124	2.000 piagas		
1.511111	38	AXT338164	AXT438124	3,000 pieces		
	40	AXT340164	AXT440124			
	44	AXT344164	AXT444124			
	50	AXT350164	AXT450124			
	54	AXT354164	AXT454124			
	56	AXT356164	AXT456124			
	60	AXT360164	AXT460124			
	70	AXT370164	AXT470124			
	80	AXT380164	AXT480124			
	90	AXT390164	AXT490124			
	100	AXT300164	AXT400124			
2.0mm	30	AXT330264	AXT430324	2 000 piocos	6 000 piasas	
3.0mm	80	AXT380264	AXT480324	3,000 pieces	6,000 pieces	

Notes: 1. Regarding ordering units; During production: Please make orders in 1-reel units.

Samples for mounting confirmation: Available in units of 50 pieces. Please consult us. (See "Regarding sample orders to confirm proper mounting" on page 13.) Samples: Small lot orders are possible. Please consult us.

^{2.} The standard type comes without positioning bosses. Connectors with positioning bosses are available on-demand production. For this type of connector, 8th digit

of the part number changes from 6 to 5 and from 2 to 1.

3. Sockets come standard with pickup covers and headers come standard without pickup covers. Please consult us if you require sockets without pickup covers and headers with pickup covers.

4. Connectors of different mated height and different number of contacts are available on-demand production only. Please contact us for more details.

SPECIFICATIONS

1. Characteristics

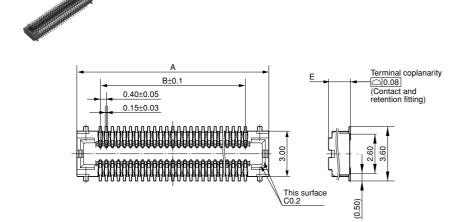
ltem		Specifications	Conditions		
	Rated current	0.3A/contact (Max. 5 A at total contacts)	_		
	Rated voltage	60V AC/DC	_		
Electrical characteristics	Breakdown voltage	150V AC for 1 min.	Rated voltage is applied for one minute and check for short circuit or damage with a detection current of 1mA.		
	Insulation resistance	Min. 1,000M Ω (initial)	Using 250V DC megger (applied for 1 min.)		
	Contact resistance	Max. 90mΩ	Measured based on the HP4338B measurement method of JIS C 5402		
	Ambient temperature	-55°C to +85°C	No freezing at low temperatures		
	Soldering heat resistance	Max. peak temperature of 260°C	Infrared reflow soldering		
	Soldering near resistance	300°C within 5 sec. or 350°C within 3 sec.	Soldering iron		
	Storage temperature	-55°C to +85°C (product only) -40°C to +50°C (emboss packing)	No freezing at low temperatures		
Environmental characteristics	Thermal shock resistance (header and socket mated)	5 cycles, insulation resistance min. 100M Ω , contact resistance max. 90m Ω	Sequence 1. –55 $^{\circ}$ °C, 30 minutes 2. $^{\circ}$, Max. 5 minutes 3. 85 $^{\circ}$ °C, 30 minutes 4. $^{\circ}$, Max. 5 minutes		
	Humidity resistance (header and socket mated)	120 hours, insulation resistance min. 100M Ω , contact resistance max. 90m Ω	Temperature 40±2°C, humidity 90 to 95% R.H.		
	Saltwater spray resistance (header and socket mated)	24 hours, insulation resistance min. 100M Ω , contact resistance max. 90m Ω	Temperature 35±2°C, saltwater concentration 5±1%		
	H ₂ S resistance (header and socket mated)	48 hours, contact resistance max. 90mΩ	Temperature 40±2°C, gas concentration 3±1 ppm, humidity 75 to 80% R.H.		
Lifetime characteristics	Insertion and removal life	50 times	Repeated insertion and removal speed of max. 200 times/hours		

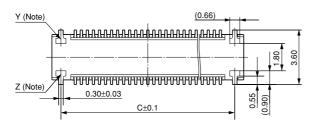
2. Material and surface treatment

Part name Material		Surface treatment				
Molded portion LCP resin (UL94V-0)		_				
Contact and Post	Copper alloy	Contact portion: Ni plating on base, Au plating on surface Terminal portion: Ni plating on base, Au plating on surface (Except for front edge of terminal) However, the area adjacent to the socket terminal is exposed to Ni on base. Retension fitting portion; Socket: Ni plating on base, Pd + Au flash plating on surface (Expect for front edge of terminal) Header: Ni plating on base, Au plating on surface (Expect for front edge of terminal)				

DIMENSIONS (mm)

- 1. Socket (Mated height: 1.5mm, 3.0mm)
- · Without pickup cover





General tolerance: ±0.2

Dimension table (mm)

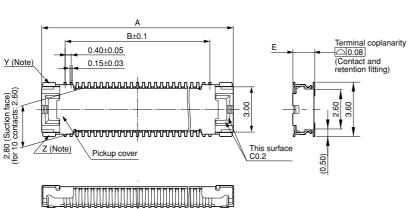
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Number of contacts/ dimension	Α	В	С
10	4.7	1.6	3.5
16	5.9	2.8	4.7
20	6.7	3.6	5.5
22	7.1	4.0	5.9
24	7.5	4.4	6.3
26	7.9	4.8	6.7
28	8.3	5.2	7.1
30	8.7	5.6	7.5
32	9.1	6.0	7.9
34	9.5	6.4	8.3
36	9.9	6.8	8.7
38	10.3	7.2	9.1
40	10.7	7.6	9.5
44	11.5	8.4	10.3
50	12.7	9.6	11.5
54	13.5	10.4	12.3
56	13.9	10.8	12.7
60	14.7	11.6	13.5
70	16.7	13.6	15.5
80	18.7	15.6	17.5
90	20.7	17.6	19.5
100	22.7	19.6	21.5

Mated height/ dimension	E
1.5mm	1.45
3.0mm	2.45

Note: Since retention fittings are built into the body, the Y and Z parts are connected electrically.

· With pickup cover

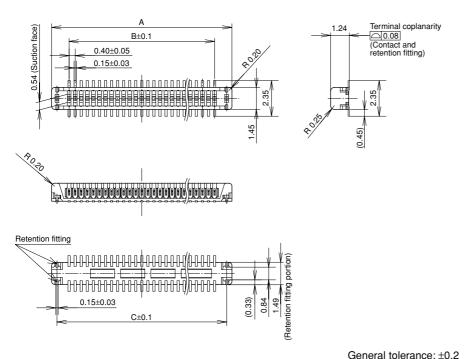




General tolerance: ±0.2

Note: Since retention fittings are built into the body, the Y and Z parts are connected electrically.



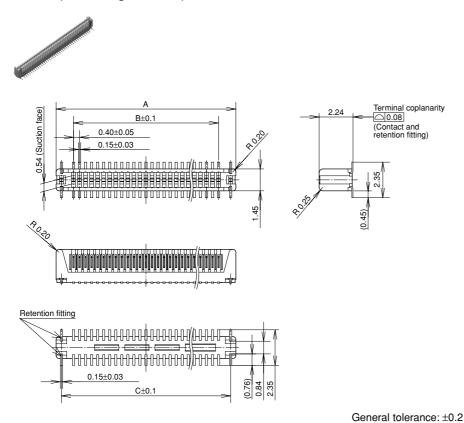


Dimension t	table	(mr	n)

(
Number of contacts/ dimension	Α	В	С
10	3.9	1.6	3.2
16	5.1	2.8	4.4
20	5.9	3.6	5.2
22	6.3	4.0	5.6
24	6.7	4.4	6.0
26	7.1	4.8	6.4
28	7.5	5.2	6.8
30	7.9	5.6	7.2
32	8.3	6.0	7.6
34	8.7	6.4	8.0
36	9.1	6.8	8.4
38	9.5	7.2	8.8
40	9.9	7.6	9.2
44	10.7	8.4	10.0
50	11.9	9.6	11.2
54	12.7	10.4	12.0
56	13.1	10.8	12.4
60	13.9	11.6	13.2
70	15.9	13.6	15.2
80	17.9	15.6	17.2
90	19.9	17.6	19.2
100	21.9	19.6	21.2

Note: The retention fitting dimensions of headers with mating heights of 1.5mm and 3.0mm are different.

3. Header (Mated height: 3.0mm)

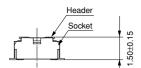


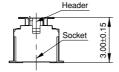
Dimension table (mm)

Number of contacts/ dimension	Α	В	С	
30	7.9	5.6	7.2	
80	17.9	15.6	17.2	

Note: The retention fitting dimensions of headers with mating heights of 1.5mm and 3.0mm are different.

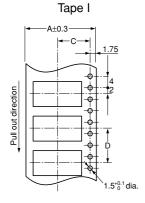
Socket and Header are mated mm

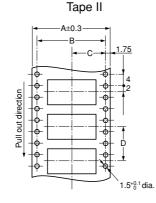


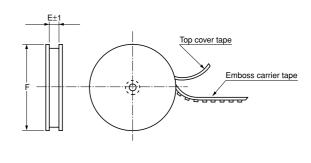


EMBOSSED TAPE DIMENSIONS (unit:mm, Common for respective contact type, socket and header)

- Tape dimensions (Conforming to JIS C 0806-1990. However, some tapes have mounting hole pitches that do not comply with the standard.)
- Reel dimensions (Conforming to EIAJ ET-7200B)



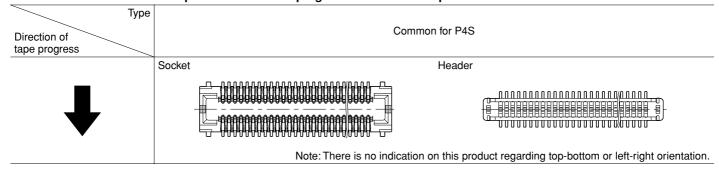




Dimension table (mm)

Mated height	Number of contacts	Type of taping	Α	В	С	D	E	F	Quantity per reel
	Max. 24	Tape I	16.0	_	7.5	8.0	17.5	φ380	3,000
Common for socket and header: 1.5mm and 3.0mm	26 to 70	Tape I	24.0	_	11.5	8.0	25.5	φ380	3,000
	72 to 100	Tape II	32.0	28.4	14.2	8.0	33.5	φ380	3,000

Connector orientation with respect to direction of progress of embossed tape

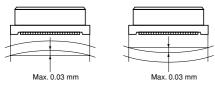


NOTES

1. As shown below, excess force during insertion may result in damage to the connector or removal of the solder. Please be careful. Also, to prevent connector damage please confirm the correct position before mating connectors.



2. Keep the PC board warp no more than 0.03mm in relation to the overall length of the connector.



3. If extra resistance to shock caused by dropping is required, we recommend using our previous P4 Series.

4. PC Boards and Recommended Metal Mask Patterns

Connectors are mounted with high density, with a pitch interval of 0.4 to 0.5mm

In order to reduce solder bridge and other issues make sure the proper levels of solder are used.

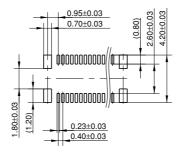
The figures to the right are recommended metal mask patterns.

Please use them as a reference.

Note: The recommended PC board pattern diagrams and metal mask pattern diagrams for headers with mating heights of 1.5mm and 3.0mm are different.

Socket

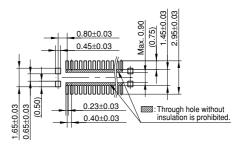
(Mated height: 1.5mm and 3.0mm)
Recommended PC board pattern (TOP VIEW)



Header

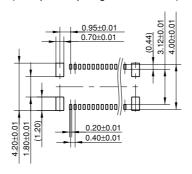
(Mated height: 1.5mm)

Recommended PC board pattern (TOP VIEW)



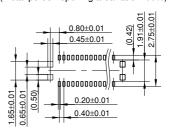
Recommended metal mask pattern

Metal mask thickness: Here, 150 μ m (Terminal portion opening area ratio: 48%) (Metal portion opening area ratio: 100%)



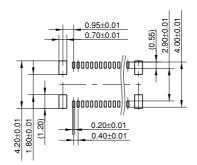
Recommended metal mask pattern

Metal mask thickness: Here, 150 μ m (Terminal portion opening area ratio: 49%) (Metal portion opening area ratio: 100%)



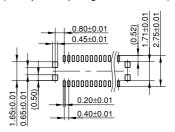
Recommended metal mask pattern

Metal mask thickness: Here, 120 μ m (Terminal portion opening area ratio: 60%) (Metal portion opening area ratio: 100%)



Recommended metal mask pattern

Metal mask thickness: Here, 120 μm (Terminal portion opening area ratio: 60%) (Metal portion opening area ratio: 100%)



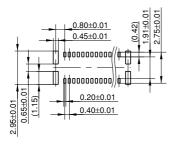
Header (Mated height: 3.0mm) Recommended PC board pattern (TOP VIEW)

0.80±0.03 0.45±0.03 0.45±0.03 0.23±0.03 0.40±0.03

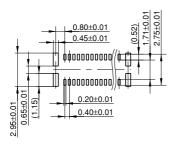
| Contact |

Note: The recommended PC board pattern diagrams and metal mask pattern diagrams for headers with mating heights of 1.5 mm and 3.0 mm are different.

Recommended metal mask pattern Metal mask thickness: Here, 150 μm (Terminal portion opening area ratio: 49%) (Metal portion opening area ratio: 100%)



Recommended metal mask pattern Metal mask thickness: Here, 120 μm (Terminal portion opening area ratio: 60%) (Metal portion opening area ratio: 100%)



Regarding general notes, please refer to page 12.

For other details, please verify with the product specification sheets.